

Title (en)

Apparatus for the placement and bonding of a die on a substrate

Title (de)

Gerät zum Positionieren und zum Verbinden einer Komponenten auf einem Substrat

Title (fr)

Appareil pour le placement et le montage d'un composant sur un substrat

Publication

EP 1174909 A3 20050126 (EN)

Application

EP 01306036 A 20010713

Priority

US 61832400 A 20000718

Abstract (en)

[origin: EP1174909A2] An apparatus (10) and method for the placement and bonding of a die (26) on a substrate (48) includes a movable die holder (24), a movable substrate holder (42), a pivoting transfer arm (30) that picks a die (26) from the movable die holder (24) and transfers the die (26) to a position adjacent the movable substrate holder (42), and a bondhead assembly (16) for picking the die (26) from the transfer arm (30) and then bonding the die (26) to the substrate (48). <IMAGE>

IPC 1-7

H01L 21/00; H05K 13/04

IPC 8 full level

H01L 21/00 (2006.01)

CPC (source: EP US)

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Citation (search report)

- [A] EP 0487336 A2 19920527 - IBM [US]
- [A] US 5667129 A 19970916 - MORITA KOICHI [JP], et al
- [A] US 5579980 A 19961203 - ICHIKAWA SHIGERU [JP]

Cited by

US11232960B2; CN107658255A; EP1775753A3; WO2005111554A3; WO2005111554A2; US7472031B2

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